Display Elektronik GmbH

DATA SHEET

LCD MODULE

DEM 240320K2 VMX-PW-N

2,8“ IPS-TFT

Product Specification

Ver.: 1

02.08.2024

Revision History

Revision	Date	Originator	Detail	Remarks
0	21.05.2024	LL	Initial Release	-
1	02.08.2024	LL	Add Weight Add Current Consumption Add CIE Valuie	P4 P5 P6

Table of Contents

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit. This TFT Module is having an universal interface pin layout to access all relevant interfaces of the TFT Driver IC. It allows to be flexible in case of TFT diver IC changes.

2. Module Parameter

Features	Details	Unit
Display Size (Diagonal)	2.8”	-
LCD Type	IPS TFT	-
Display Mode	Transmissive / Normally Black	-
Resolution	240 x RGB x 320	Pixels
Module Outline	50.00 x 69.20 x 2.5 (Note1)	mm
Active Area	43.20 x 57.60	mm
Pixel Size	0.180 x 0.180	mm
Pixel Arrangement	RGB Vertical Stripe	-
Polarizer Surface Treatment	Anti-Glare	-
Display Colors	262k	-
Interface	8/9/16/18 MPU Interface or 3-wire 9-bit Interface + RGB Interface or 4-wire 8-bit Interface + RGB Interface	-
With or without Touch Panel	Without	-
Driver IC	ST7789T3 (Sitronix)	-
Operating Temperature	-30°C ~ +80°C	ºC
Storage Temperature	-30°C ~ +80°C	ºC
Weight	~ 15	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25ºC

Item		Symbol	Min.	Max.	Unit
Supply Voltage	Logic	IOVCC	-0.3	4.6	V
	Analog	VCC	-0.3	4.6	V
Storage Temperature		T_{STG}	-30	+80	ºC
Operating Temperature		T_{OP}	-30	+80	ºC

Note 1: If Ta below 50ºC, the maximal humidity is 90%RH, if Ta over 50ºC, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item		Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	Logic	IOVCC	1.65	1.8/2.8	3.3	V
	Analog	VCC	2.4	2.8	3.3	V
Logic Low Input Voltage		V_{IL}	GND	-	0.3*IOVCC	V
Logic High Input Voltage		V_{IH}	0.7*IOVCC	-	IOVCC	V
Logic Low Output Voltage		V_{OL}	GND	-	0.2*IOVCC	V
Logic High Output Voltage		V_{OH}	0.8*IOVCC	-	IOVCC	V
Current Consumption All White	Logic	I_{CC+} I_{IN}	-	7	-	mA
	Analog					

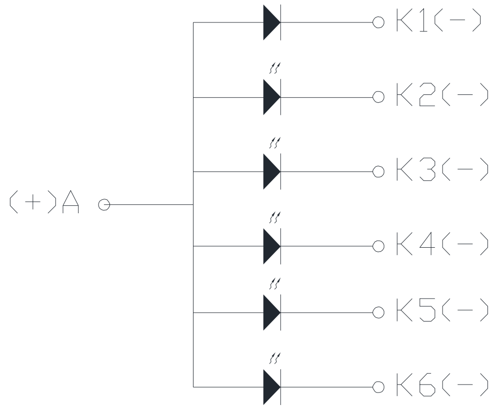
5. Backlight Characteristic

5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	Ta=25 ºC, I_F=20mA/LED	2.9	3.2	3.4	V
Forward Current	I_F	Ta=25 ºC, V_F=3.2V/LED	-	120		mA
Power dissipation	P_D		-	384	-	mW
LED Life Time(25 ºC)	-	-	-	50,000	-	Hr
Uniformity	Avg		-	80	-	%
Drive method	Constant Current					
LED Configuration	6 White LEDs in parallel					

Note: LED Lifetime defined as follows: The final brightness is at 50% of original brightness.
The environmental conducted under ambient air flow, at Ta=25°C ± 2ºC, 60%RH±5%, I_F=20mA/LED.

5.2. Backlighting Circuit



6. Optical Characteristics

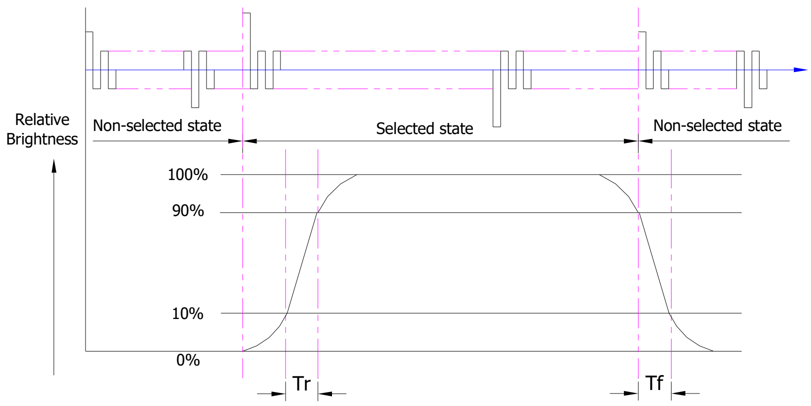
6.1. Optical Characteristics

Ta=25ºC, VCC=2.8V

	Item		Symbol	Condition	Specification Min.	Specification Typ.	Specification Max.	Unit
Backlight On (Transmissive Mode)	Luminance On TFT(I_f =20mA/LED)		Lv	Normally viewing angle θX = φY =0º	580	720	-	cd/m²
	Contrast Ratio (See 6.3)		CR		1000	1200	-	
	Response Time (See 6.2)		T_R+T_F		-	30	35	ms
	Chromaticity Transmissive (See 6.5)	Red	X_R		0.615	0.665	0.715	-
			Y_R		0.280	0.330	0.380	-
		Green	X_G		0.268	0.318	0.368	-
			Y_G		0.602	0.652	0.702	-
		Blue	X_B		0.070	0.120	0.170	-
			Y_B		0.062	0.112	0.162	-
		White	X_W		0.255	0.305	0.355	-
			Y_W		0.307	0.357	0.407	-
	Viewing Angle (See 6.4)	Horizontal	θX+	Center CR≥10	75	80	-	Deg.
			θX-		75	80	-	
		Vertical	φY+		75	80	-	
			φY-		75	80	-	
	NTSC Ratio(Gamut)				65	70	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

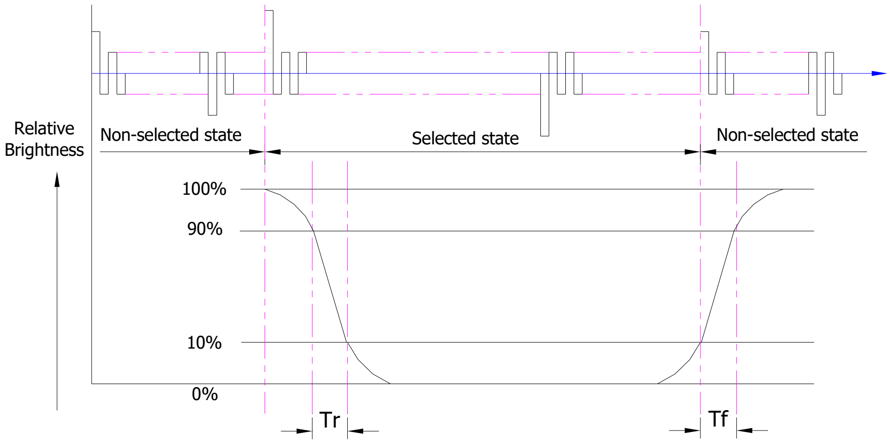


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;
Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;
Note: Measuring machine: LCD-5100 or EQUI

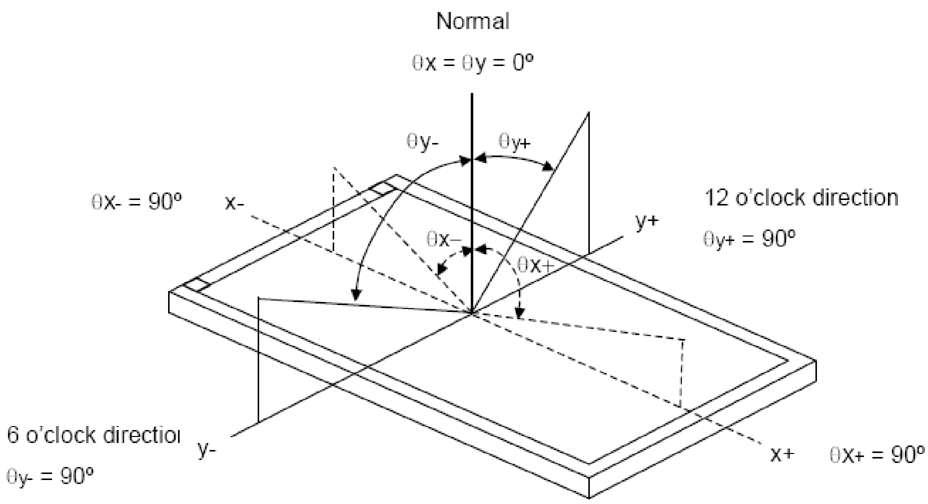
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test Pattern	A: All Pixels white
	B: All Pixel black
Contrast Setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



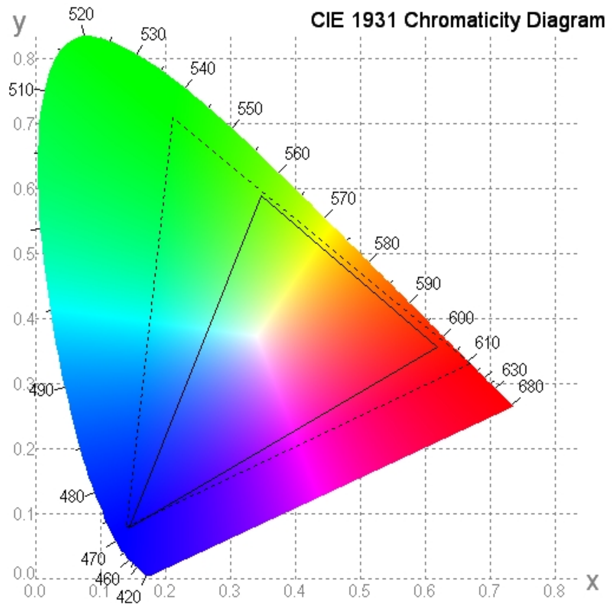
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

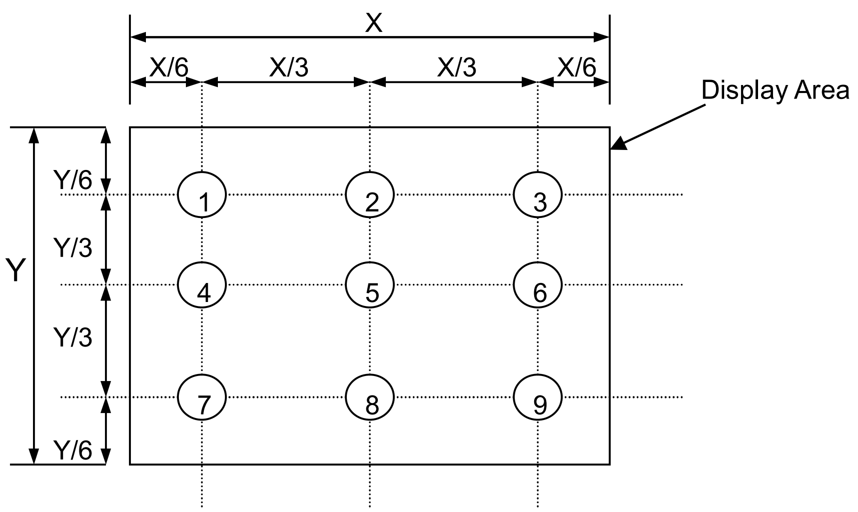
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: L_V = average (L_{P1}:L_{P9})

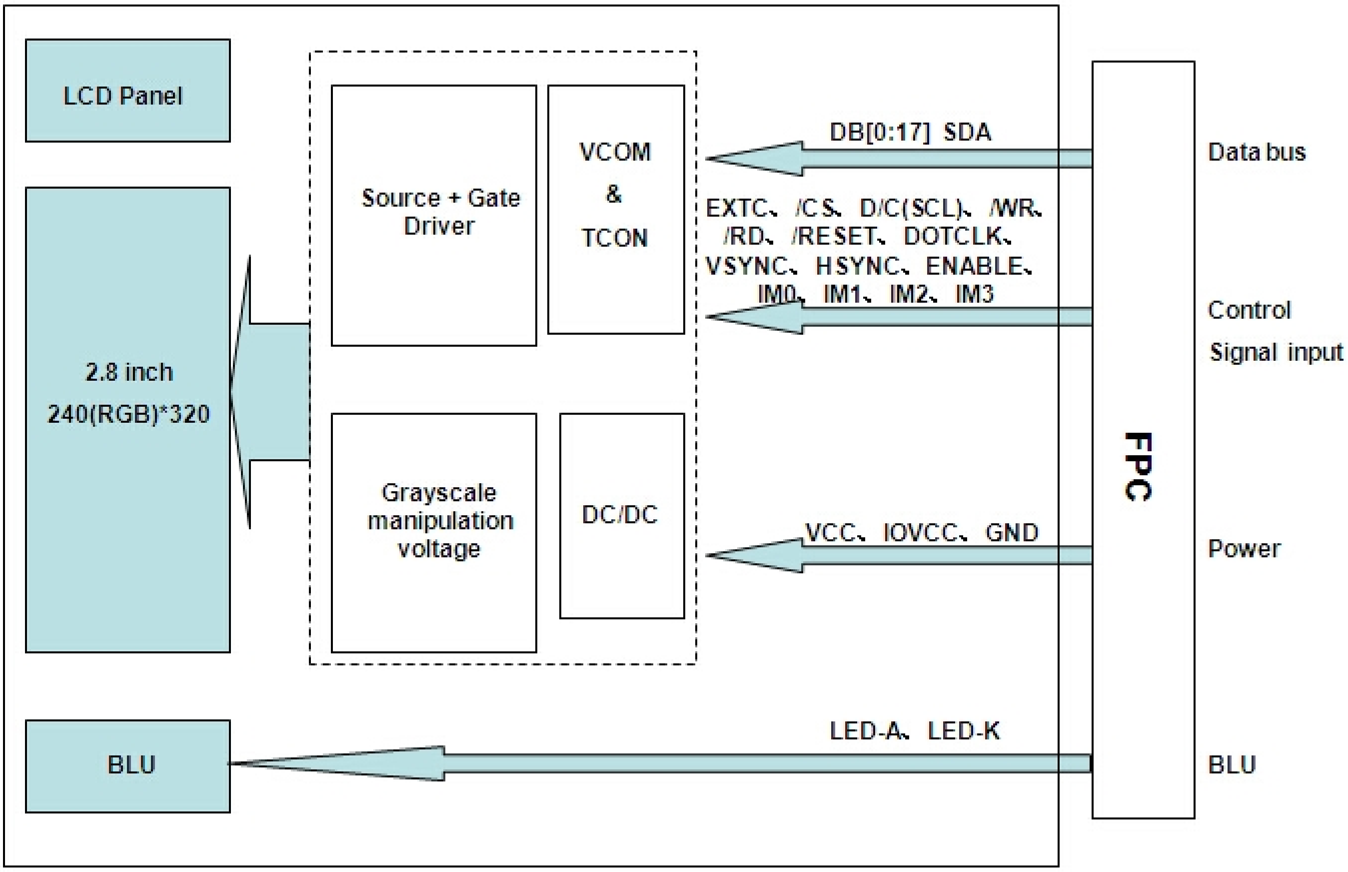
6.6.2. Uniformity = Minimal (L_{P1}:L_{P9}) / Maximal (L_{P1}:L_{P9}) * 100%

6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

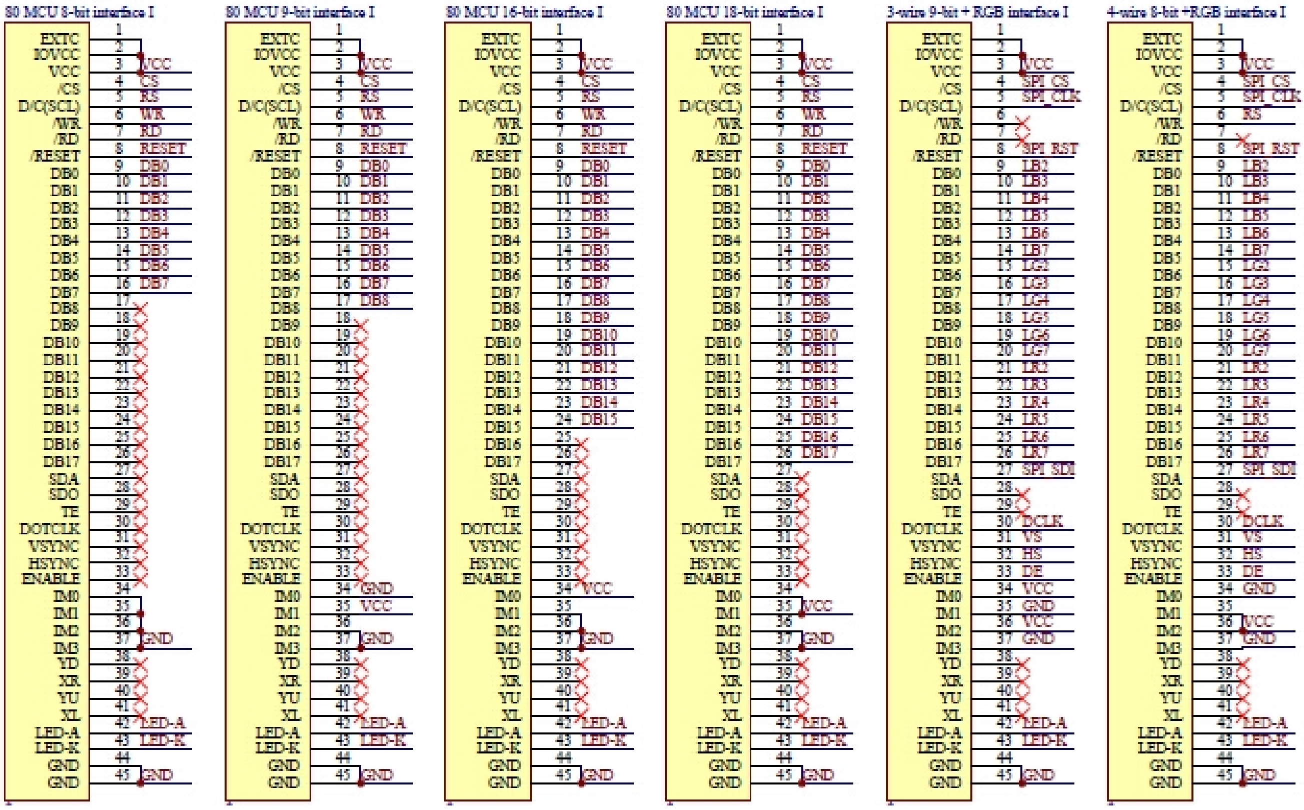


8. Interface Pins Definition

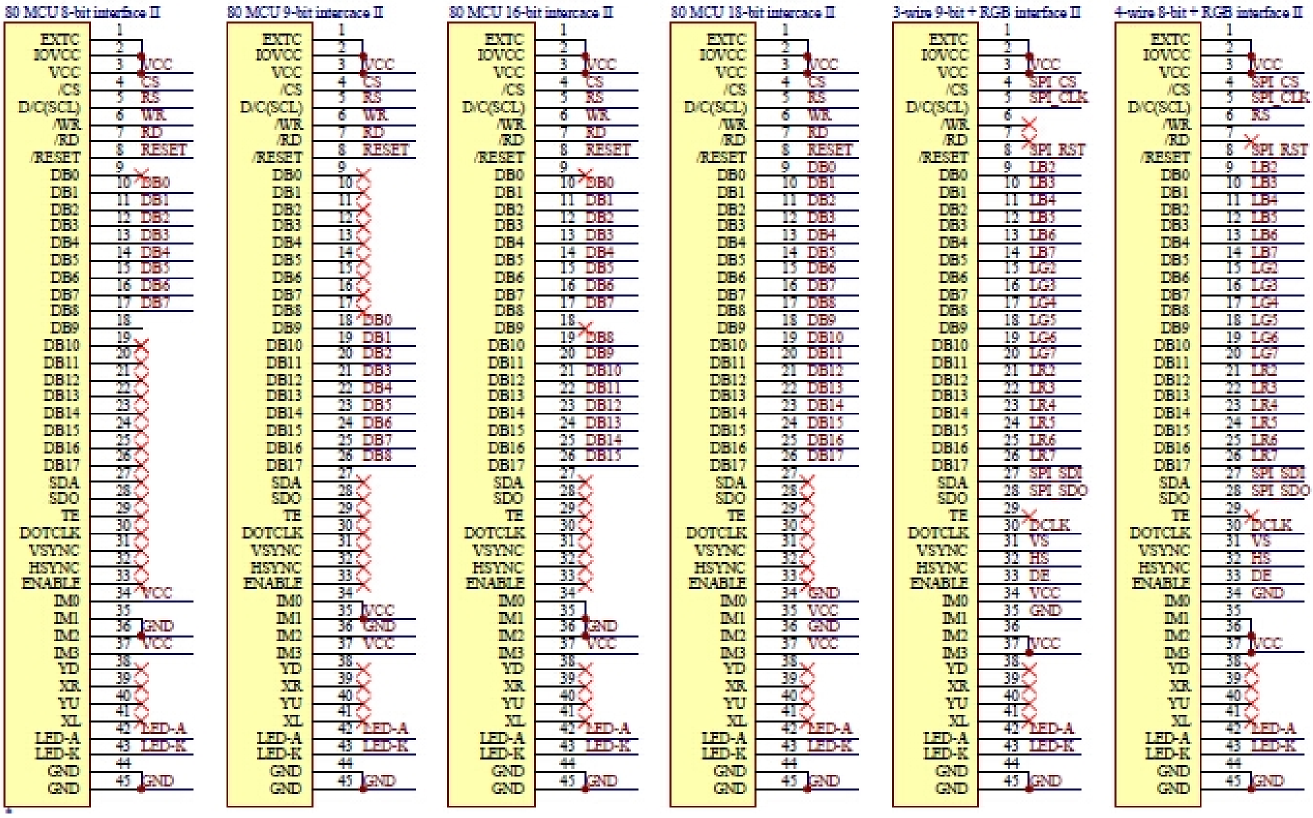
No.	Symbol	Function
1	EXTC	Extended command set enable. High: extended command set is accepted. EXTC must be set “H” to read/write extended registers.
2	IOVCC(1.8/2.8V)	Digital Supply Power.
3	VCC(2.8V)	Analog Supply Power.
4	/CS	Chip Select Signal (Low: active).
5	D/C(SCL)	D/C: Data/Commander Selection. SCL: Serial clock in 3-wire 9-bit/4-wire 8-bit serial data interface.
6	/WR	8080-system: Serves as Write Signal. 4-line system: Serves as the selector of command or parameter.
7	/RD	Read Signal.
8	/RESET	Reset Signal.
9	DB0	Data Bus.
10	DB1	Data Bus.
11	DB2	Data Bus.
12	DB3	Data Bus.
13	DB4	Data Bus.
14	DB5	Data Bus.
15	DB6	Data Bus.
16	DB7	Data Bus.
17	DB8	Data Bus.
18	DB9	Data Bus.
19	DB10	Data Bus.
20	DB11	Data Bus.
21	DB12	Data Bus.
22	DB13	Data Bus.
23	DB14	Data Bus.
24	DB15	Data Bus.
25	DB16	Data Bus.
26	DB17	Data Bus.
27	SDA	SPI interface input pin.
28	SDO	SPI interface output pin.
29	TE	Tearing effect output pin to synchronize MPU to frame writing, active by S/W command.
30	DOTCLK	Pixel clock signal in RGB I/F mode.
31	VSYNC	Vertical sync. Signal in RGB I/F mode.
32	HSYNC	Horizontal sync. Signal in RGB I/F mode.
33	ENABLE	Data enable signal in RGB I/F mode.

<table>
<tr><td>34-37</td><td>IM0
IM1
IM2
IM3</td><td>
<table>
<tr><th rowspan="2">IM3</th><th rowspan="2">IM2</th><th rowspan="2">IM1</th><th rowspan="2">IM0</th><th rowspan="2">MPU interface Mode</th><th colspan="2">DB pin</th></tr>
<tr><th>Register</th><th>Gram</th></tr>
<tr><td>0</td><td>0</td><td>0</td><td>0</td><td>80 MCU 8-bit bus interface I</td><td>DB[7:0]</td><td>DB[7:0]</td></tr>
<tr><td>0</td><td>0</td><td>0</td><td>1</td><td>80 MCU 16-bit bus interface I</td><td>DB[7:0]</td><td>DB[15:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>0</td><td>80 MCU 9-bit bus interface I</td><td>DB[7:0]</td><td>DB[8:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>1</td><td>80 MCU 18-bit bus interface I</td><td>DB[7:0]</td><td>DB[17:0]</td></tr>
<tr><td>0</td><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data Serial interface I</td><td colspan="2">SDA: in/out</td></tr>
<tr><td>0</td><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data Serial interface I</td><td colspan="2">SDA: in/out</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>0</td><td>80 MCU 16-bit bus interface II</td><td>DB[8:1]</td><td>DB[8:1]
DB[17:10]</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>1</td><td>80 MCU 8-bit bus interface II</td><td>DB[17:10]</td><td>DB[17:10]</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>0</td><td>80 MCU 18-bit bus interface II</td><td>DB[8:1]</td><td>DB[17:0]</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>1</td><td>80 MCU 9-bit bus interface II</td><td>DB[17:10]</td><td>DB[17:9]</td></tr>
<tr><td>1</td><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data Serial interface II</td><td colspan="2">SDI: in
SDO: out</td></tr>
<tr><td>1</td><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data Serial interface II</td><td colspan="2">SDI: in
SDO: out</td></tr>
</table>
</td></tr>
<tr><td>38</td><td>NC(YD)</td><td>No connection.</td></tr>
<tr><td>39</td><td>NC(XR)</td><td>No connection.</td></tr>
<tr><td>40</td><td>NC(YU)</td><td>No connection.</td></tr>
<tr><td>41</td><td>NC(XL)</td><td>No connection.</td></tr>
<tr><td>42</td><td>LED-A</td><td>LED Anode.</td></tr>
<tr><td>43</td><td>LED-K</td><td>LED Cathode.</td></tr>
<tr><td>44</td><td>GND</td><td>Ground.</td></tr>
<tr><td>45</td><td>GND</td><td>Ground.</td></tr>
</table>

80 MCU Interface I

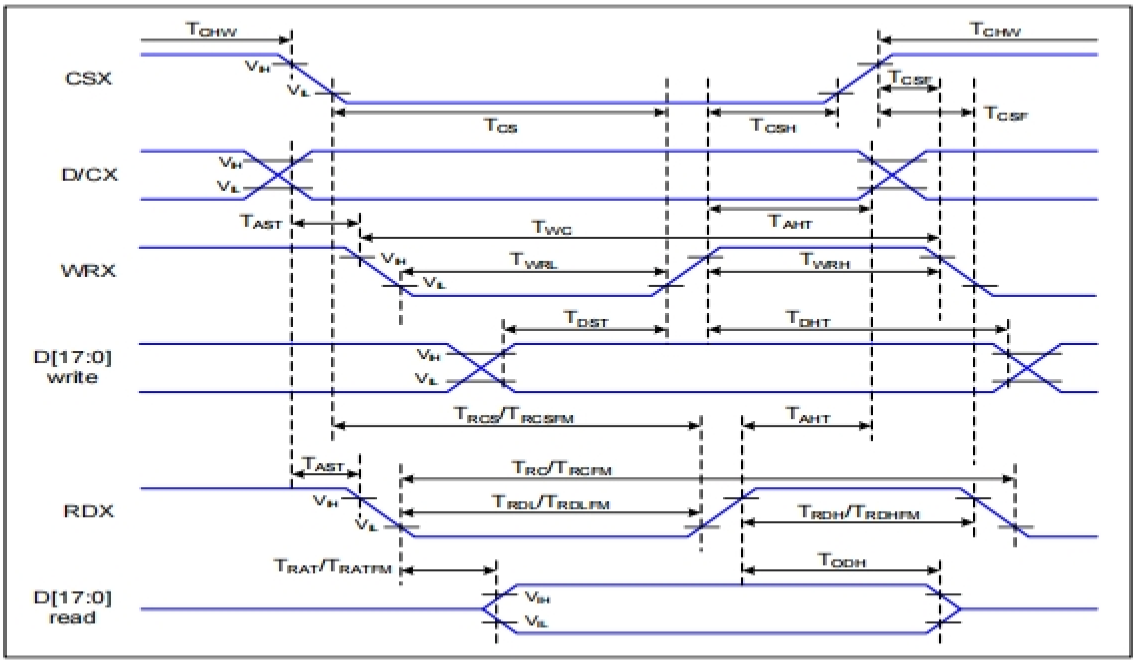


80 MCU Interface II



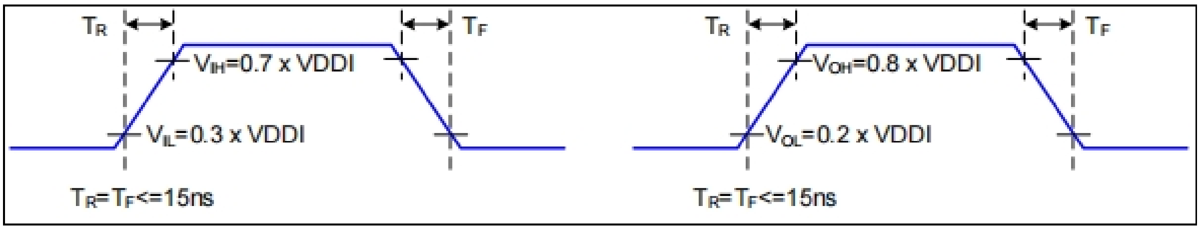
9. AC Characteristics

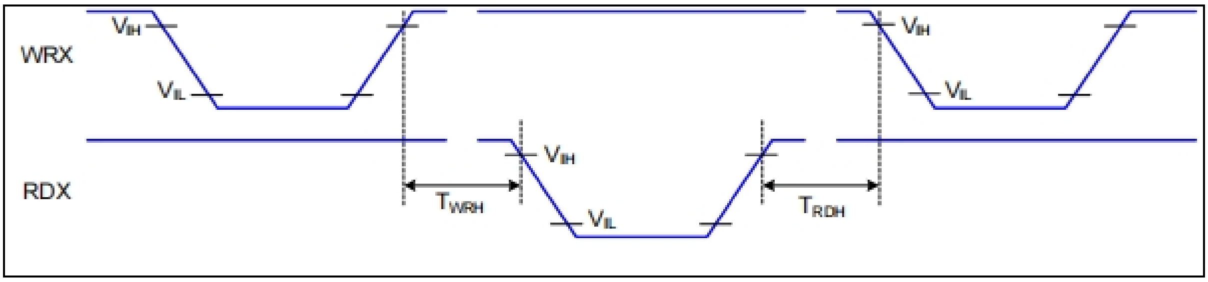
9.1 Display Parallel 18/16/9/8-Bit Interface Timing Characteristics



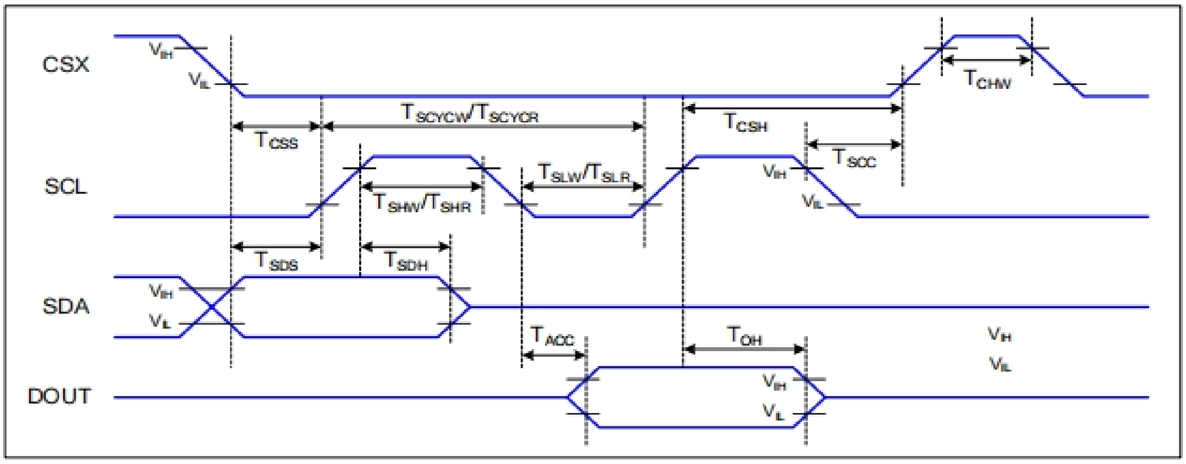
Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	0		ns	-
	T_{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T_{CHW}	Chip select "H" pulse width	0		ns	-
	T_{CS}	Chip select setup time (Write)	15		ns	
	T_{RCS}	Chip select setup time (Read ID)	45		ns	
	T_{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T_{CSF}	Chip select wait time (Write/Read)	10		ns	
	T_{CSH}	Chip select hold time	10		ns	
WRX	T_{WC}	Write cycle	66		ns	
	T_{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T_{RC}	Read cycle (ID)	160		ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	90		ns	
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T_{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T_{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T_{DST}	Data setup time	10		ns	For CL=30pF

	T_{DHT}	Data hold time	10		ns	
	T_{RAT}	Read access time (ID)		40	ns	
	T_{RATFM}	Read access time (FM)		340	ns	
	T_{ODH}	Output disable time	20	80	ns	





9.3 Display Serial Interface Timing Characteristics (3-line SPI System)

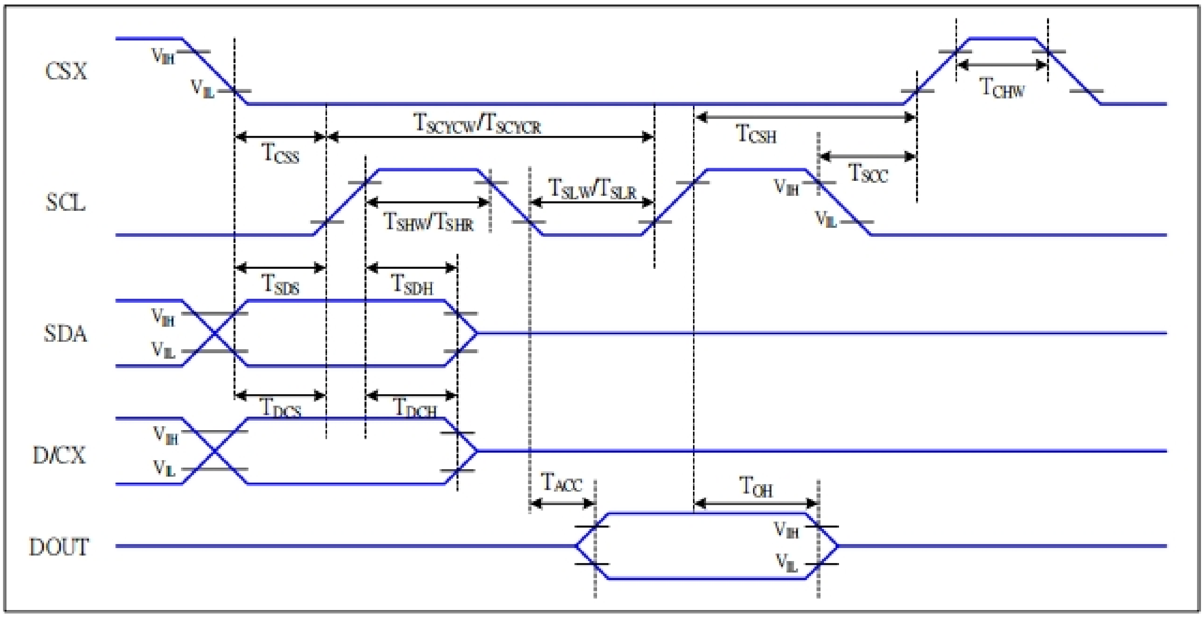


Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	16		ns	
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Note1 : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals

Note2: In the read sequence of serial interface, the 500nsec delay time is needed between read command and first read clock..

9.4 Display Serial Interface Timing Characteristics (4-line SPI System)

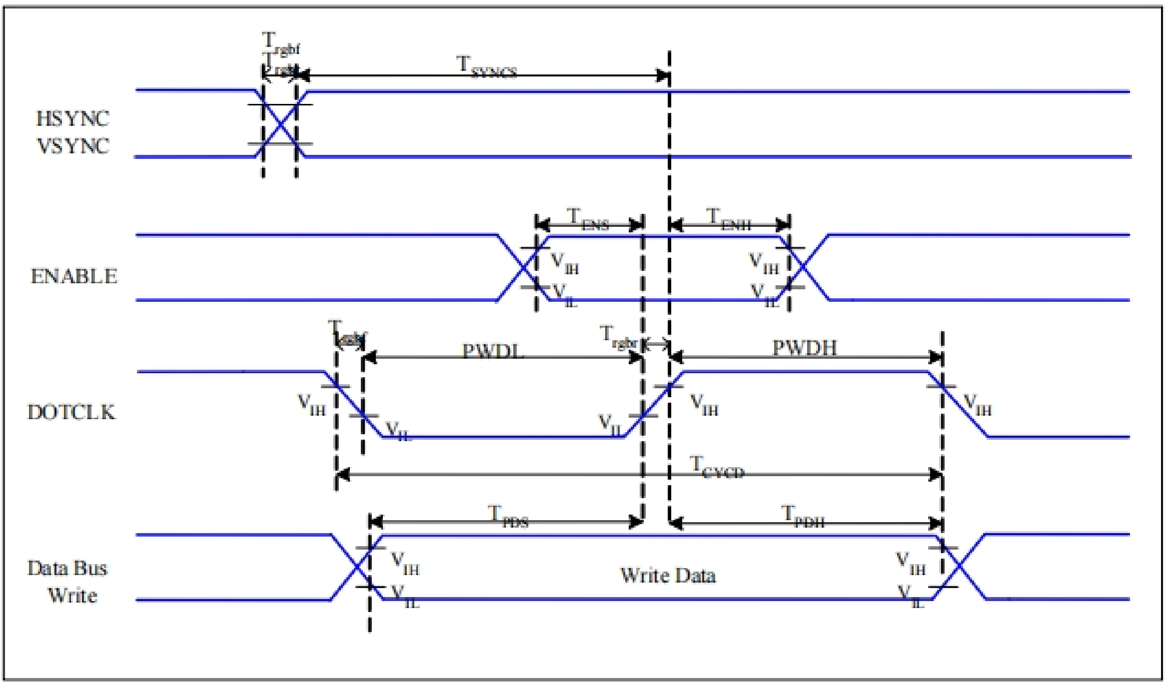


Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	TCSS	Chip select setup time (write)	15		ns	
	TCSH	Chip select hold time (write)	15		ns	
	TCSS	Chip select setup time (read)	60		ns	
	TSCC	Chip select hold time (read)	65		ns	
	TCHW	Chip select "H" pulse width	40		ns	
SCL	TSCYCW	Serial clock cycle (Write)	16		ns	-write command & data ram
	TSHW	SCL "H" pulse width (Write)	7		ns	
	TSLW	SCL "L" pulse width (Write)	7		ns	
	TSCYCR	Serial clock cycle (Read)	150		ns	-read command & data ram
	TSHR	SCL "H" pulse width (Read)	60		ns	
	TSLR	SCL "L" pulse width (Read)	60		ns	
D/CX	TDCS	D/CX setup time	10		ns	
	TDCH	D/CX hold time	10		ns	
SDA (DIN)	TSDS	Data setup time	7		ns	
	TSDH	Data hold time	7		ns	
DOUT	TACC	Access time	10	50	ns	For maximum CL=30pF
	TOH	Output disable time	15	50	ns	For minimum CL=8pF

Note1 : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals

Note2: In the read sequence of serial interface, the 500nsec delay time is needed between read command and first read clock.

9.5 RGB Interface Timing Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	
	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T_{PDS}	PD Data Setup Time	50	-	ns	
	T_{PDH}	PD Data Hold Time	50	-	ns	

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	35	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	35	-	ns	
	T_{ENH}	Enable Hold Time	35	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	35	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	35	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	80	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	10	ns	
DB	T_{PDS}	PD Data Setup Time	35	-	ns	
	T_{PDH}	PD Data Hold Time	35	-	ns	

10. Command Table

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
NOP	0	↑	1	-	0	0	0	0	0	0	0	0	(00h)	No operation
SWRESET	0	↑	1	-	0	0	0	0	0	0	0	1	(01h)	Software reset
RDDID	0	↑	1	-	0	0	0	0	0	1	0	0	(04h)	Read display ID
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	ID17	ID16	ID15	ID14	ID13	ID12	ID11	ID10		ID1 read
	1	1	↑	-	ID27	ID26	ID25	ID24	ID23	ID22	ID21	ID20		ID2 read
	1	1	↑	-	ID37	ID36	ID35	ID34	ID33	ID32	ID31	ID30		ID3 read
RDDST	0	↑	1	-	0	0	0	0	1	0	0	1	(09h)	Read display status
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	BSTON	MY	MX	MV	ML	RGB	MH	ST24		-
	1	1	↑	-	ST23	IFPF2	IFPF1	IFPF0	IDMON	PTLON	SLOUT	NORON		-
	1	1	↑	-	ST15	ST14	INVON	ST12	ST11	DISON	TEON	GCS2		-
	1	1	↑	-	GCS1	GCS0	TEM	ST4	ST3	ST2	ST1	ST0		-
RDDPM	0	↑	1	-	0	0	0	0	1	0	1	0	(0Ah)	Read display power
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	BSTON	IDMON	PTLON	SLPOUT	NORON	DISON	0	0		
RDD MADCTL	0	↑	1	-	0	0	0	0	1	0	1	1	(0Bh)	Read display
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	MY	MX	MV	ML	RGB	MH	0	0		-
RDD COLMOD	0	↑	1	-	0	0	0	0	1	1	0	0	(0Ch)	Read display pixel
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	0	D6	D5	D4	0	D2	D1	D0		-
RDDIM	0	↑	1	-	0	0	0	0	1	1	0	1	(0Dh)	Read display image
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	VSSON	0	INVON	0	0	GC2	GC1	GC0		-
RDDSM	0	↑	1	-	0	0	0	0	1	1	1	0	(0Eh)	Read display signal
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
	1	1	↑	-	TEON	TEM	0	0	0	0	0	0		-
RDDSDR	0	↑	1	-	0	0	0	0	1	1	1	1	(0Fh)	Read display self-diagnostic result
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	D7	D6	0	0	0	0	0	0		-
SLPIN	0	↑	1	-	0	0	0	1	0	0	0	0	(10h)	Sleep in
SLPOUT	0	↑	1	-	0	0	0	1	0	0	0	1	(11h)	Sleep out
PTLON	0	↑	1	-	0	0	0	1	0	0	1	0	(12h)	Partial mode on
NORON	0	↑	1	-	0	0	0	1	0	0	1	1	(13h)	Partial off (Normal)
INVOFF	0	↑	1	-	0	0	1	0	0	0	0	0	(20h)	Display inversion off
INVON	0	↑	1	-	0	0	1	0	0	0	0	1	(21h)	Display inversion on
GAMSET	0	↑	1	-	0	0	1	0	0	0	0	1	(26h)	Display inversion on
	1	↑	1	-	0	0	0	0	GC3	GC2	GC1	GC0		
DISPOFF	0	↑	1	-	0	0	1	0	1	0	0	0	(28h)	Display off
DISPON	0	↑	1	-	0	0	1	0	1	0	0	1	(29h)	Display on
CASET	0	↑	1	-	0	0	1	0	1	0	1	0	(2Ah)	Column address set
	1	↑	1	-	XS15	XS14	XS13	XS12	XS11	XS10	XS9	XS8		X address start: 0≤ XS≤ X
	1	↑	1		XS7	XS6	XS5	XS4	XS3	XS2	XS1	XS0		
	1	↑	1		XE15	XE14	XE13	XE12	XE11	XE10	XE9	XE8		X address start: S≤ XE≤ X
	1	↑	1		XE7	XE6	XE5	XE4	XE3	XE2	XE1	XE0		
RASET	0	↑	1	-	0	0	1	0	1	0	1	1	(2Bh)	Row address set
	1	↑	1	-	YS15	YS14	YS13	YS12	YS11	YS10	YS9	YS8		Y address start: 0≤ YS≤ Y
	1	↑	1		YS7	YS6	YS5	YS4	YS3	YS2	YS1	YS0		
	1	↑	1		YE15	YE14	YE13	YE12	YE11	YE10	YE9	YE8		Y address start: S≤ YE≤ Y
	1	↑	1		YE7	YE6	YE5	YE4	YE3	YE2	YE1	YE0		
RAMWR	0	↑	1	-	0	0	1	0	1	1	0	0	(2Ch)	Memory write
	1	↑	1	D1[17:8]	D1[7]	D1[6]	D1[5]	D1[4]	D1[3]	D1[2]	D1[1]	D1[0]		Write data
	1	↑	1	Dx[17:8]	Dx[7]	Dx[6]	Dx[5]	Dx[4]	Dx[3]	Dx[2]	Dx[1]	Dx[0]		
	1	↑	1	Dn[17:8]	Dn[7]	Dn[6]	Dn[5]	Dn[4]	Dn[3]	Dn[2]	Dn[1]	Dn[0]		
RAMRD	0	↑	1	-	0	0	1	0	1	1	1	0	(2Eh)	Memory read

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	D1[17:8]	D1[7]	D1[6]	D1[5]	D1[4]	D1[3]	D1[2]	D1[1]	D1[0]		Read data
	1	1	↑	Dx[17:8]	Dx[7]	Dx[6]	Dx[5]	Dx[4]	Dx[3]	Dx[2]	Dx[1]	Dx[0]		
	1	1	↑	Dn[17:8]	Dn[7]	Dn[6]	Dn[5]	Dn[4]	Dn[3]	Dn[2]	Dn[1]	Dn[0]		
PTLAR	0	↑	1	-	0	0	1	1	0	0	0	0	(30h)	Partial sart/end address set
	1	↑	1	-	PSL15	PSL14	PSL13	PSL12	PSL11	PSL10	PSL9	PSL8		Partial start address: (0, 1,2, ..P)
	1	↑	1	-	PSL7	PSL6	PSL5	PSL4	PSL3	PSL2	PSL1	PSL0		
	1	↑	1	-	PEL15	PEL14	PEL13	PEL12	PEL11	PEL10	PEL9	PEL8		Partial end address (0, 1,2, 3, , P)
	1	↑	1	-	PEL7	PEL6	PEL5	PEL4	PEL3	PEL2	PEL1	PEL0		
VSCRDEF	0	↑	1	-	0	0	1	1	0	0	1	1	(33h)	Vertical scrolling definition
	1	↑	1	-	TFA15	TFA14	TFA13	TFA12	TFA11	TFA10	TFA9	TFA8		
	1	↑	1	-	TFA7	TFA6	TFA5	TFA4	TFA3	TFA2	TFA1	TFA0		
	1	↑	1	-	VSA15	VSA14	VSA13	VSA12	VSA11	VSA10	VSA9	VSA8		
	1	↑	1	-	VSA7	VSA6	VSA5	VSA4	VSA3	VSA2	VSA1	VSA0		
	1	↑	1	-	BFA15	BFA14	BFA13	BFA12	BFA11	BFA10	BFA9	BFA8		
	1	↑	1	-	BFA7	BFA6	BFA5	BFA4	BFA3	BFA2	BFA1	BFA0		
TEOFF	0	↑	1	-	0	0	1	1	0	1	0	0	(34h)	Tearing effect line off
TEON	0	↑	1	-	0	0	1	1	0	1	0	1	(35h)	Tearing effect line on
	1	↑	1	-	-	-	-	-	-	-	-	TEM		
MADCTL	0	↑	1	-	0	0	1	1	0	1	1	0	(36h)	Memory data access control
	1	↑	1	-	MY	MX	MV	ML	RGB	0	0	0		-
VSCRSADD	0	↑	1	-	0	0	1	1	0	1	1	1	(37h)	Vertical scrolling start address
	1	↑	1	-	VSP15	VSP14	VSP13	VSP12	VSP11	VSP10	VSP9	VSP8		
	1	↑	1	-	VSP7	VSP6	VSP5	VSP4	VSP3	VSP2	VSP1	VSP0		
IDMOFF	0	↑	1	-	0	0	1	1	1	0	0	0	(38h)	Idle mode off
IDMON	0	↑	1	-	0	0	1	1	1	0	0	1	(39h)	Idle mode on

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
COLMOD	0	↑	1	-	0	0	1	1	1	0	1	0	(3Ah)	Interface pixel format
	1	↑	1	-	0	D6	D5	D4	0	D2	D1	D0		Interface format
RAMWRC	0	↑	1	-	0	0	1	1	1	1	0	0	(3Ch)	Memory write continue
	1	↑	1	D1[17:8]	D1[7]	D1[6]	D1[5]	D1[4]	D1[3]	D1[2]	D1[1]	D1[0]		Write data
	1	↑	1	Dx[17:8]	Dx[7]	Dx[6]	Dx[5]	Dx[4]	Dx[3]	Dx[2]	Dx[1]	Dx[0]		
	1	↑	1	Dn[17:8]	Dn[7]	Dn[6]	Dn[5]	Dn[4]	Dn[3]	Dn[2]	Dn[1]	Dn[0]		
RAMRDC	0	↑	1	-	0	0	1	1	1	1	1	0	(3Eh)	Memory read continue
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy Read
	1	1	↑	D1[17:8]	D1[7]	D1[6]	D1[5]	D1[4]	D1[3]	D1[2]	D1[1]	D1[0]		
	1	1	↑	Dx[17:8]	Dx[7]	Dx[6]	Dx[5]	Dx[4]	Dx[3]	Dx[2]	Dx[1]	Dx[0]		
	1	1	↑	Dn[17:8]	Dn[7]	Dn[6]	Dn[5]	Dn[4]	Dn[3]	Dn[2]	Dn[1]	Dn[0]		
TESCAN	0	↑	1	-	0	1	0	0	0	1	0	0	(44h)	Set tear scanline
	1	↑	1	-	N15	N14	N13	N12	N11	N10	N9	N8		
	1	↑	1	-	N7	N6	N5	N4	N3	N2	N1	N0		
RDTESCAN	0	↑	1	-	0	1	0	0	0	1	0	1	(45h)	Get scanline
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy Read
	1	1	↑	-	-	-	-	-	-	-	N9	N8		
	1	1	↑	-	N7	N6	N5	N4	N3	N2	N1	N0		
WRDISBV	0	↑	1	-	0	1	0	1	0	0	0	1	(51h)	Write display brightness
	1	↑	1	-	DBV7	DBV6	DBV5	DBV4	DBV3	DBV2	DBV1	DBV0		
RDDISBV	0	↑	1	-	0	1	0	1	0	0	1	0	(52h)	Read display brightness value
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	DBV7	DBV6	DBV5	DBV4	DBV3	DBV2	DBV1	DBV0		
WRCTRLD	0	↑	1	-	0	1	0	1	0	0	1	1	(53h)	Write CTRL display
	1	↑	1	-	0	0	BCTRL	0	DD	BL	0	0		
RDCTRLD	0	↑	1	-	0	1	0	1	0	1	0	0	(54h)	Read CTRL value dsiplay
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	0	0	BCTRL	0	DD	BL	0	0		

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
WRCACE	0	↑	1	-	0	1	0	1	0	1	0	1	(55h)	Write content adaptive brightness control and Color enhancemnet
	1	↑	1	-	CECTRL	0	CE1	CE0	0	0	C1	C0		
RDCABC	0	↑	1	-	0	1	0	1	0	1	1	0	(56h)	Read content adaptive brightness control
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	0	CECTRL	0	0	0	0	C1	C0		
WRCABCMB	0	↑	1	-	0	1	0	1	1	1	1	0	(5Eh)	Write CABC minimum brightness
	1	↑	1	-	CMB7	CMB6	CMB5	CMB4	CMB3	CMB2	CMB1	CMB0		
RDCABCMB	0	↑	1	-	0	1	0	1	1	1	1	1	(5Fh)	Read CABC minimum brightness
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	CMB7	CMB6	CMB5	CMB4	CMB3	CMB2	CMB1	CMB0		
RDABCSDR	0	↑	1	-	0	1	1	0	1	0	0	0	(68h)	Read Automatic Brightness Control Self-Diagnostic Result
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	D7	D6	0	0	0	0	0	0		-
RDID1	0	↑	1	-	1	1	0	1	1	0	1	0	(DAh)	Read ID1
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	ID17	ID16	ID15	ID14	ID13	ID12	ID11	ID10		Read parameter
RDID2	0	↑	1	-	1	1	0	1	1	0	1	1	(DBh)	Read ID2
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑	-	ID27	ID26	ID25	ID24	ID23	ID22	ID21	ID20		Read parameter
RDID3	0	↑	1	-	1	1	0	1	1	1	0	0	(DCh)	Read ID3

Instruction	D/CX	WRX	RDX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex	Function
	1	1	↑	-	-	-	-	-	-	-	-	-		Dummy read
	1	1	↑		ID37	ID36	ID35	ID34	ID33	ID32	ID31	ID30		Read parameter

11. Quality Assurance

11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3. Nonconforming Analysis & Disposition

11.3.1. Nonconforming analysis:

11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

11.3.2. Disposition of nonconforming:

11.3.2.1. Non-conforming product over PPM level will be replaced.

11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

11.4.1. There is any discrepancy in standard of quality assurance.

11.4.2. Additional requirement to be added in product specification.

11.4.3. Any other special problem.

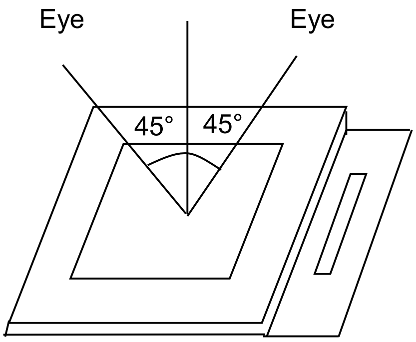
11.5. Standard of the Product Visual Inspection

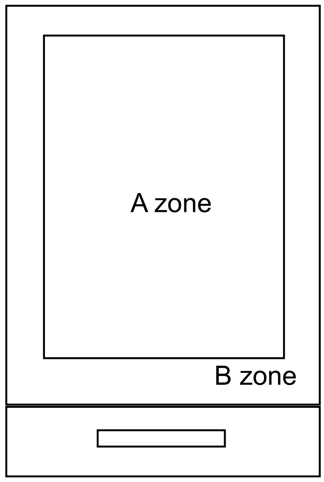
11.5.1. Appearance inspection:

11.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



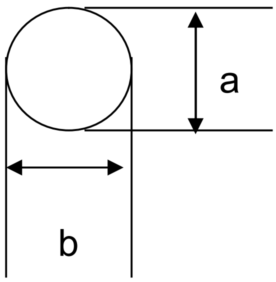


11.5.2. Basic principle:

11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

11.5.2.2. New item must be added on time when it is necessary.

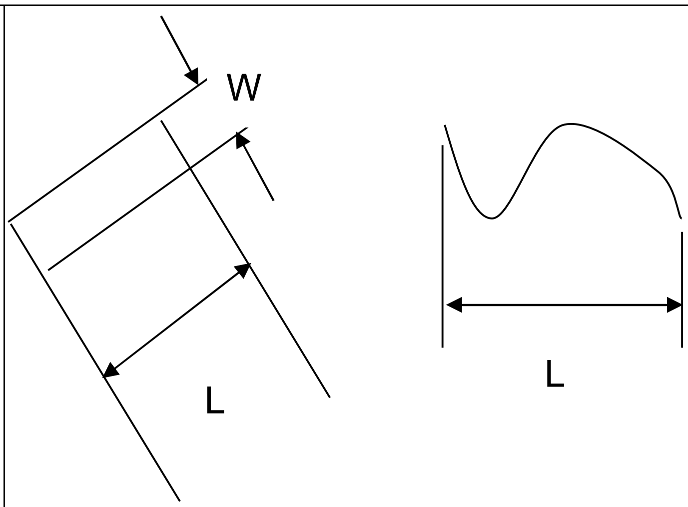
11.6.Inspection Specification

<table>
<tr><th>No.</th><th>Item</th><th>Criteria (Unit: mm)</th></tr>
<tr><td>01</td><td>Black / White spot
Foreign material
(Round type)
Pinholes
Stain
Particles inside cell.
(Minor defect)</td><td>

φ= (a + b) /2
<table>
<tr><th>Area / Size</th><th>Acc. Qty</th></tr>
<tr><td>φ≤0.10</td><td>Ignore</td></tr>
<tr><td>0.10<φ≤0.15</td><td>2</td></tr>
<tr><td>0.15<φ≤0.25</td><td>1</td></tr>
<tr><td>0.25<φ</td><td>0</td></tr>
<tr><td>Total</td><td>2 no include
φ≤ 0.10</td></tr>
</table>
Distance between 2 defects should more than 3mm apart.</td></tr>
<tr><td>02</td><td>Electrical Defect
(Minor defect)</td><td><table>
<tr><th></th><th>Display Area</th><th>Total</th><th></th></tr>
<tr><td>Bright dot</td><td>0</td><td>0</td><td rowspan="3">Note1</td></tr>
<tr><td>Dark dot</td><td>N≦2</td><td>N≦2</td></tr>
<tr><td>Total dot</td><td>N≦2</td><td>N≦2</td></tr>
<tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td>Note 2</td></tr>
</table>
Remark:
1. Bright dot caused by scratch and foreign object accords to item 1.</td></tr>
</table>

03

Black and White line
Scratch
Foreign material
(Line type)
(Minor defect)

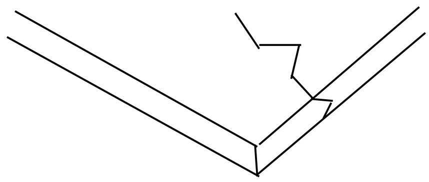


Length	Width	Acc. Qty
/	W ≦ 0.03	Ignore
L ≦ 2.5	0.03 ＜ W ≦ 0.05	3
L ≦ 2.5	0.05 ＜ W ≦ 0.10	2
/	0.1 ＜ W	0
Total		3

Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.

04

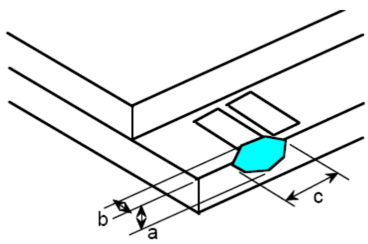
Glass Crack
(Minor defect)



Crack is potential to enlarge, any type is not allowed.

05

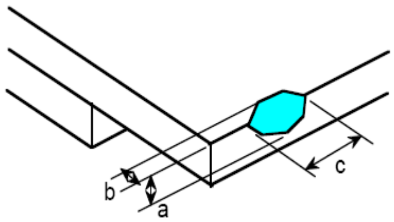
Glass Chipping Pad Area:
(Minor defect)



Length and Width	Acc. Qty
c > 3.0, b< 1.0	1
c< 3.0, b< 1.0	3
a<Glass Thickness	

06

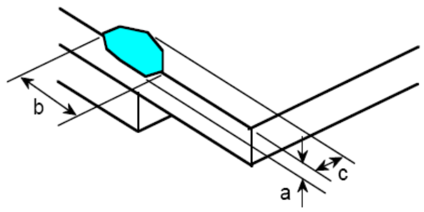
Glass Chipping Rear of Pad Area:
(Minor defect)



Length and Width	Acc. Qty
c > 3.0, b< 1.0	1
c< 3.0, b< 1.0	2
c< 3.0, b< 0.5	4
a<Glass Thickness	

07

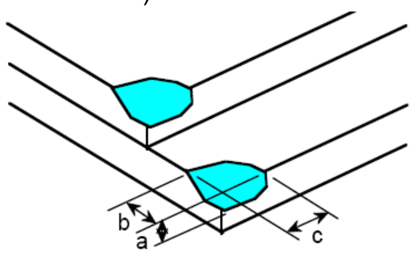
Glass Chipping Except Pad Area:
(Minor defect)



Length and Width	Acc. Qty
c > 3.0, b< 1.0	1
c< 3.0, b< 1.0	2
c< 3.0, b< 0.5	4
a<Glass Thickness	

08

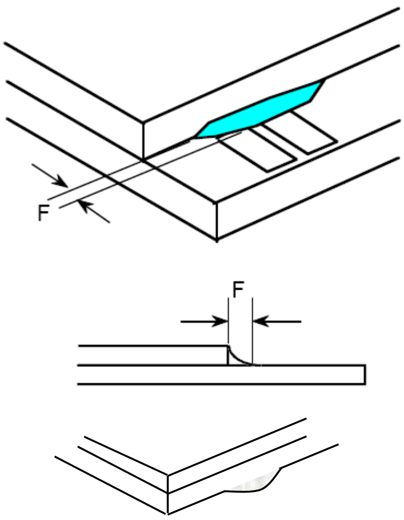
Glass Corner Chipping:
(Minor defect)



Length and Width	Acc. Qty
c < 3.0, b< 3.0	Ignore
a<Glass Thickness	

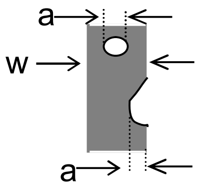
09

Glass Burr:
(Minor defect)



Length	Acc. Qty
F < 1.0	Ignore

Glass burr don't affect assemble and module dimension.

<table>
<tr><td>10</td><td>FPC Defect:
(Minor defect)

</td><td>10.1 Dent, pinhole width a<w/3.
(w: circuitry width.)
10.2 Open circuit is unacceptable.
10.3 No oxidation, contamination and distortion.</td></tr>
<tr><td>11</td><td>Bubble on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>12</td><td>Dent on Polarizer
(Minor defect)</td><td><table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>13</td><td>Bezel</td><td>13.1 No rust, distortion on the Bezel.
13.2 No visible fingerprints, stains or other contamination.</td></tr>
<tr><td>14</td><td>PCB</td><td>14.1 No distortion or contamination on PCB terminals.
14.2 All components on PCB must same as documented on the BOM/component layout.
14.3 Follow IPC-A-600F.</td></tr>
<tr><td>15</td><td>Soldering</td><td>Follow IPC-A-610C standard</td></tr>
<tr><td>16</td><td>Electrical Defect
(Major defect)</td><td>The below defects must be rejected.
16.1 Missing vertical / horizontal segment,
16.2 Abnormal Display.
16.3 No function or no display.
16.4 Current exceeds product specifications.
16.5 LCD viewing angle defect.
16.6 No Backlight.
16.7 Dark Backlight.
16.8 Touch Panel no function.</td></tr>
</table>

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

11.7.2. Two minor defects are equal to one major in lot sampling inspection.

11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

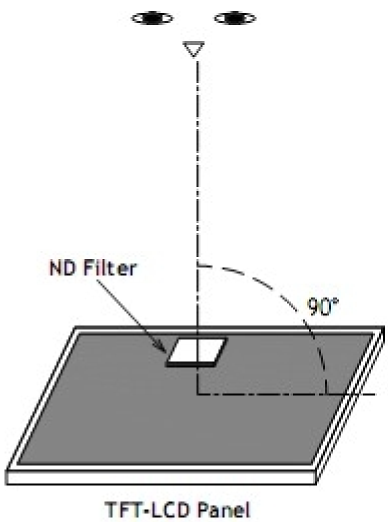
11.9. Packing

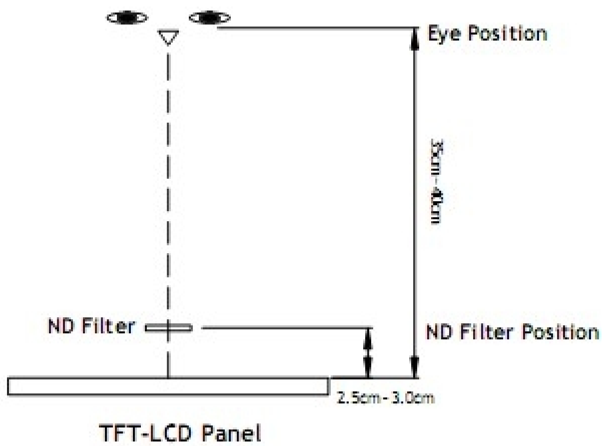
11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

11.9.2. Modules inside package box should have compliant mark.

11.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.





Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	80°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-30°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air:±8KV 150pF/330Ω 5 times Contact:±4KV 150pF/330Ω 5 times	2	GB/T17626.2 -2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7-2018

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value.

13. Precautions and Warranty

13.1. Safety

13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2. Handling

13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.

13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3. Storage

13.3.1. Do not store the LCD module beyond the specified temperature ranges.

13.3.2. Strong light exposure causes degradation of polarizer and color filter.

13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

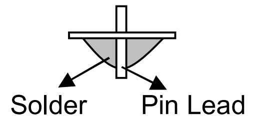
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

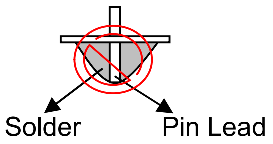
Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



Recommended



Not Recommended

13.4.2. Pins of EL

13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270～290℃

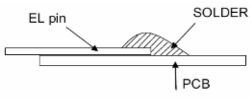
Typical Soldering Time: ≤2s

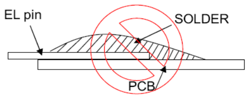
Minimum solder distance from EL lamp (body):2.0mm

13.4.2.4. No horizontal press on the EL leads during soldering.

13.4.2.5. 180° bend EL leads three times is not allowed.

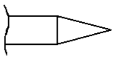
13.4.2.6. Solder Wetting

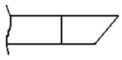




Recommended Not Recommended

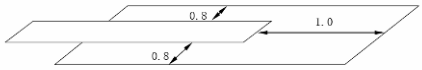
13.4.2.7. The type of the solder iron:





Recommended Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

13.5.1. Do not drive LCD with DC voltage

13.5.2. Response time will increase below lower temperature

13.5.3. Display may change color with different temperature

13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.

13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.

13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.

13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.

13.5.8. Do not display the fixed pattern for long time（we suggest the time not longer than one hour because it will develop image sticking due to the TFT structure.

13.6. Static Electricity

13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.

13.6.2. The normal static prevention measures should be observed for work clothes and benches.

13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7. Limited Warranty

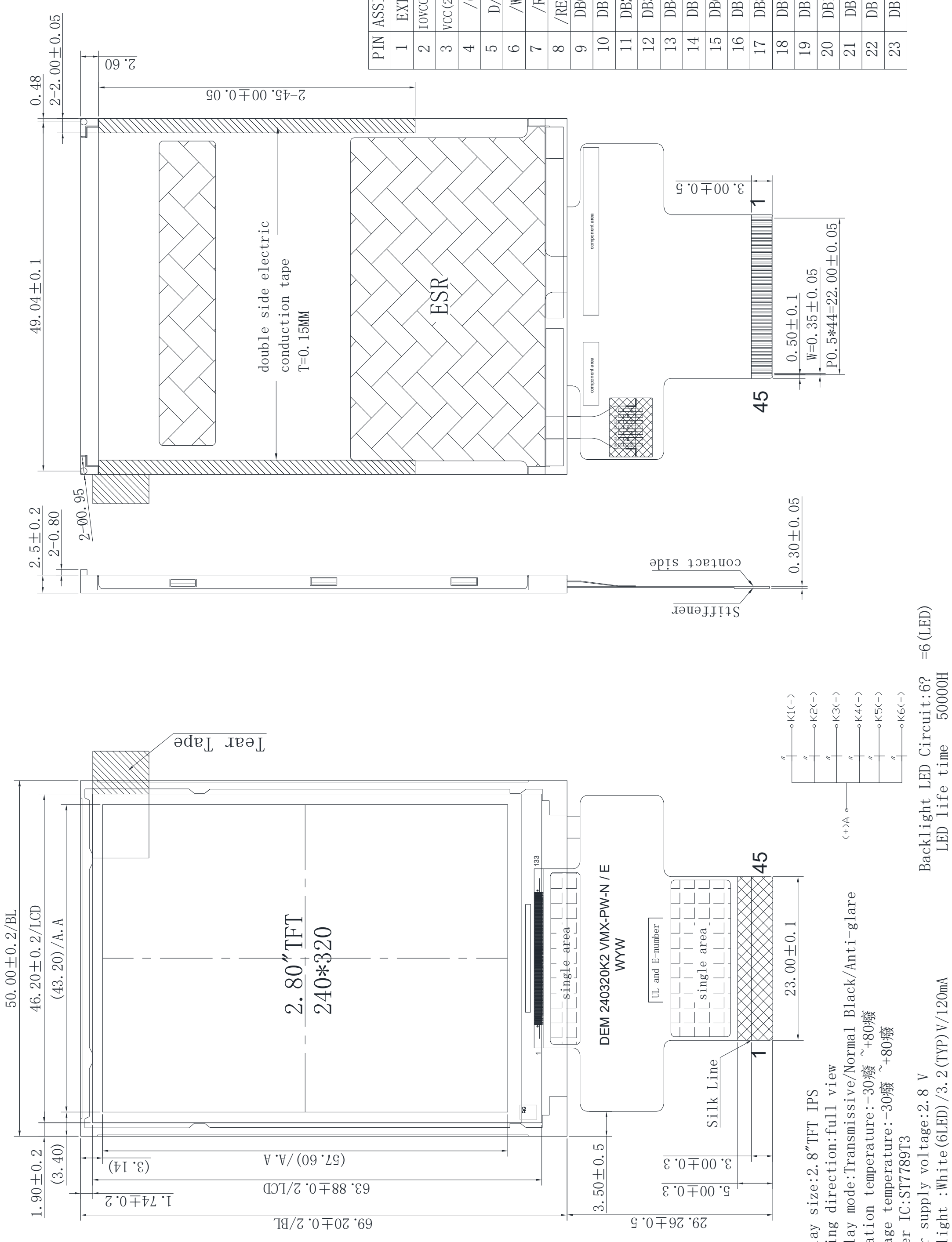
13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.

13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.

13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Outline Drawing

PIN	ASSIGNMENT	PIN	ASSIGNMENT
1	EXTC	24	DB15
2	IOVCC(1.8/2.8V)	25	DB16
3	VCC(2.8V)	26	DB17
4	/CS	27	SDA
5	D/C(SCL)	28	SDO
6	/WR	29	TE
7	/RD	30	DOTCLK
8	/RESET	31	VSYNC
9	DB0	32	HSYNC
10	DB1	33	ENABLE
11	DB2	34	IM0
12	DB3	35	IM1
13	DB4	36	IM2
14	DB5	37	IM3
15	DB6	38	NC(YD)
16	DB7	39	NC(XR)
17	DB8	40	NC(YU)
18	DB9	41	NC(XL)
19	DB10	42	LED_A
20	DB11	43	LED_K
21	DB12	44	GND
22	DB13	45	GND
23	DB14		



NOTES:
1.Display size:2.8"TFT IPS
2.Viewing direction:full view
3.Display mode:Transmissive/Normal Black/Anti-glare
4.Operation temperature:-30癈~+80癈
5.Storage temperature:-30癈~+80癈
6.Driver IC:ST7789T3
7.Power supply voltage:2.8 V
8.Backlight :White(6LED)/3.2(TYP)V/120mA
9.LCM Luminance:720(TYP)cd/m²
10.Interface type:IM0-IM3 Pull out the optional MCU,SPI,RGB
11.RoHS must be complied
* The dimension with mark brackets "()" just for reference